

Local Alignment of the BaBar Silicon Vertex Tracking Detector

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For
BaBar Collaboration

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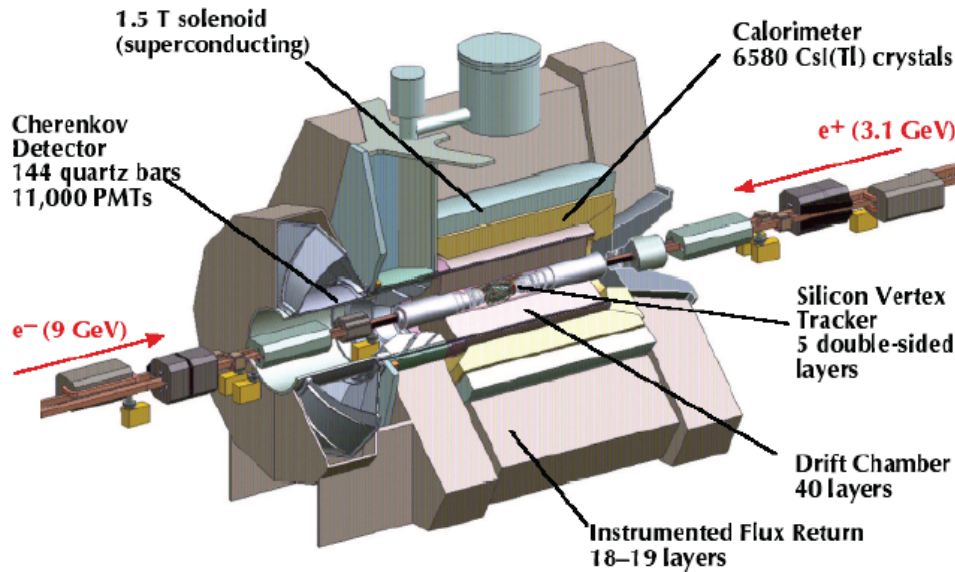




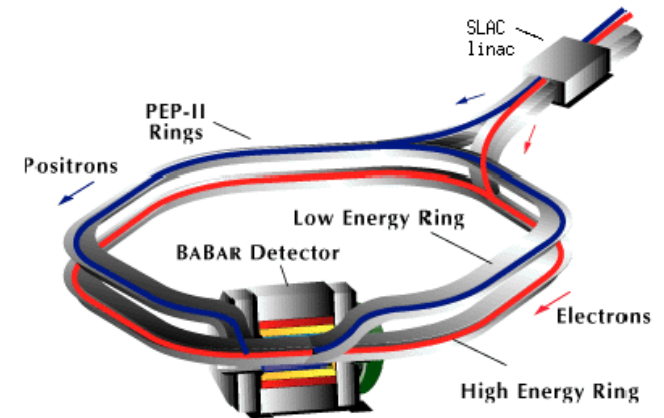
The BaBar Experiment



- **Silicon Vertex Tracker (SVT)**: 5 layers of double-sided Si
- **Drift chamber (DCH)**: P measurement and particle ID through dE/dX (low P)
- **Detector of Internally Reflected Cherenkov Light (DIRC)**: particle ID (high P)
- **Electromagnetic calorimeter (EMC)**: π^0 and K^0 -long reconstruction, e ID
- **Instrumented Flux Return (IFR)**: μ ID and K^0 -long reconstruction
- **Trigger**: Two levels: L1 up to 2 KHz, L3 up to 100 Hz
- **Offline software and event store**: C++ and Object Oriented databases

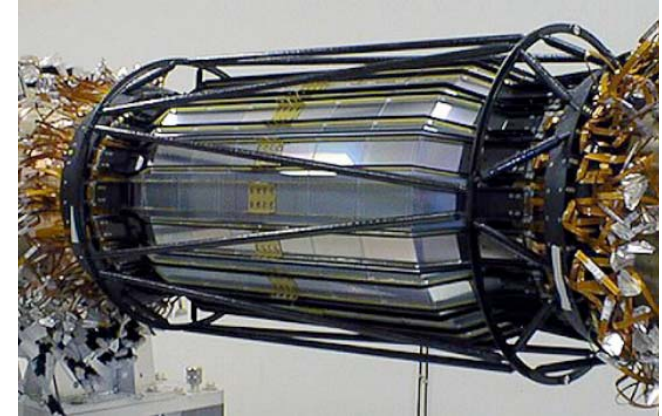
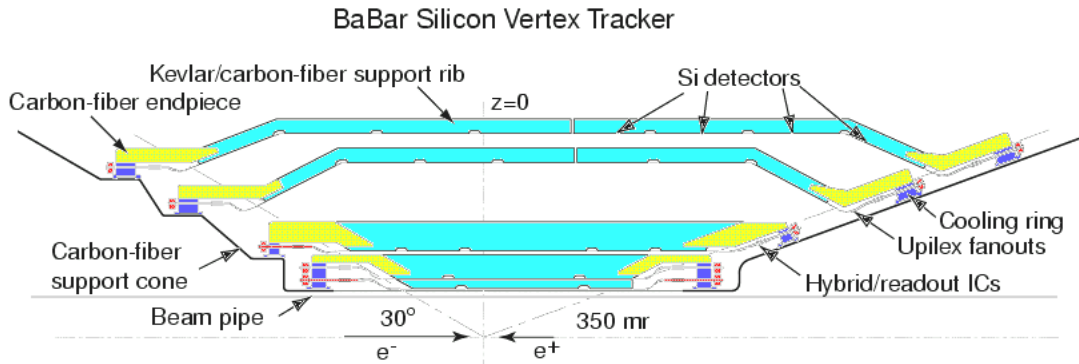


BABAR Detector



PEP-II

The Silicon Vertex Tracker



- 340 double-sided Si wafers $\sim 1\text{m}^2$ Si
- 5 layers independent tracker
- Unique 'arch' in outer layer inner three layers planar
- CF support structure
- 4% X_0 total
- $\sim 90\%$ of Ω
- Mounted on the innermost magnets

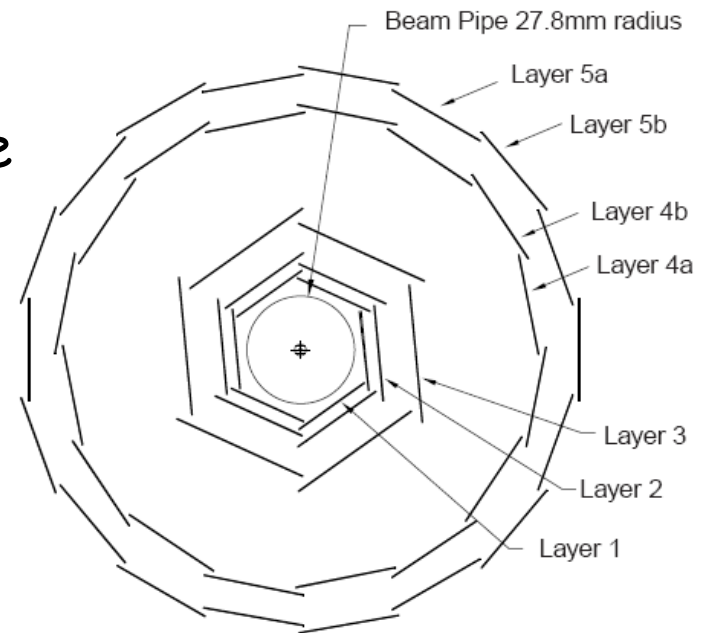
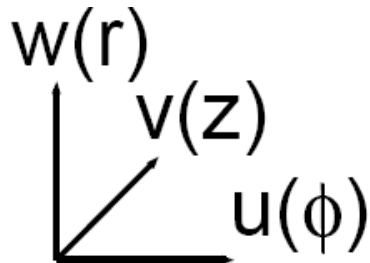
layer	wafers in module	modules in layer	radius (mm)	z (L) (mm)	ϕ (W) (mm)
1	4	6	32	42	41
2	4	6	40	45	49
3	6	6	54	44	71
4	7	16	91-127	54-68	43-53
5	8	18	114-144	68	43-53



Parameterizing the SVT Local Alignment

- Determine precise relative position of silicon sensors:
6 parameters for each of **340** SVT wafers
3 translations and **3 rotations**
- Complex process:
 - calculate hit **residuals**, minimize

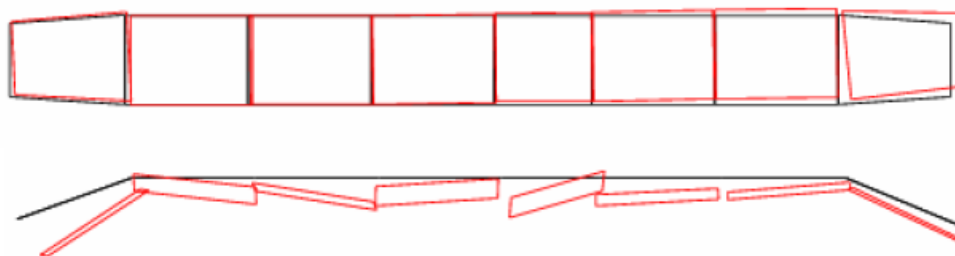
$$\chi^2 \equiv \sum_i^{\text{hits}} \epsilon_i^T (\Delta \mathbf{p}) \mathbf{V}_i^{-1} \epsilon_i (\Delta \mathbf{p})$$





Optical Survey Constraint in SVT-LA

- We use optical survey information in module plane:



- Important addition to track residual information
- Compute wafer residuals with respect to survey
- χ^2 in module plane (u , v , R_w) weight 1.0 5 μ m
in out-of-module plane: (w , R_u , R_v) weight 0.1 20 μ m

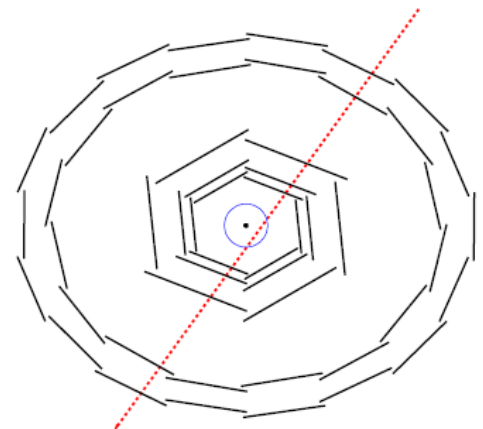
- (1) Constrain wafers within modules
- (2) Constrain dead readout (Z or/and ϕ) wafers



SVT-LA Goals and Requirements



- Determine the **local alignment** parameters with sufficient accuracy
average resolution: $10\mu\text{m}$ for u hits and $20\mu\text{m}$ for ν hits
statistical precision and control the **systematic** errors
- **Track-based** and **lab-bench** measurements only constrain the relative positions of nearby wafers
raise the risk of introducing a '**global distortion**'
- Following the **time-dependence** of the actual changes in the detector
- Quickly detect when the local alignment changes



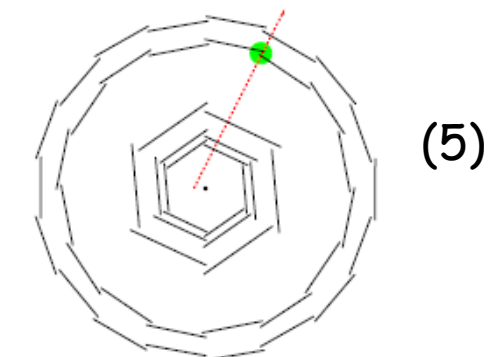
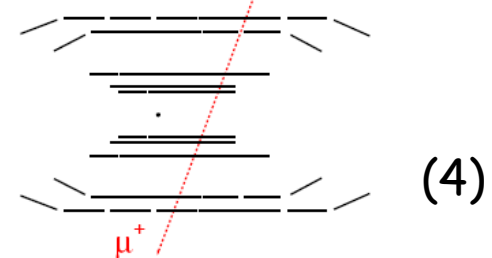
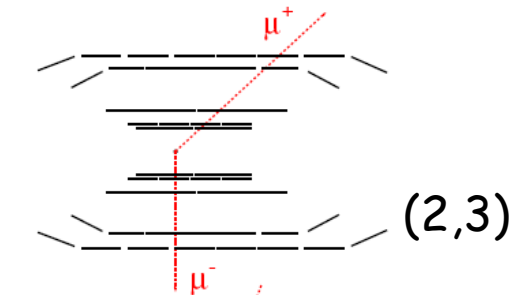
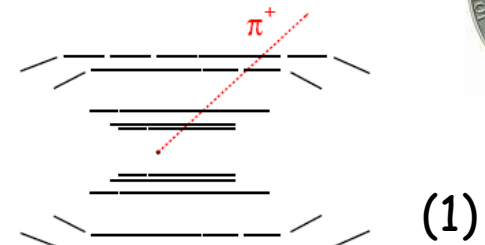


Track/Hit Selection for SVT-LA



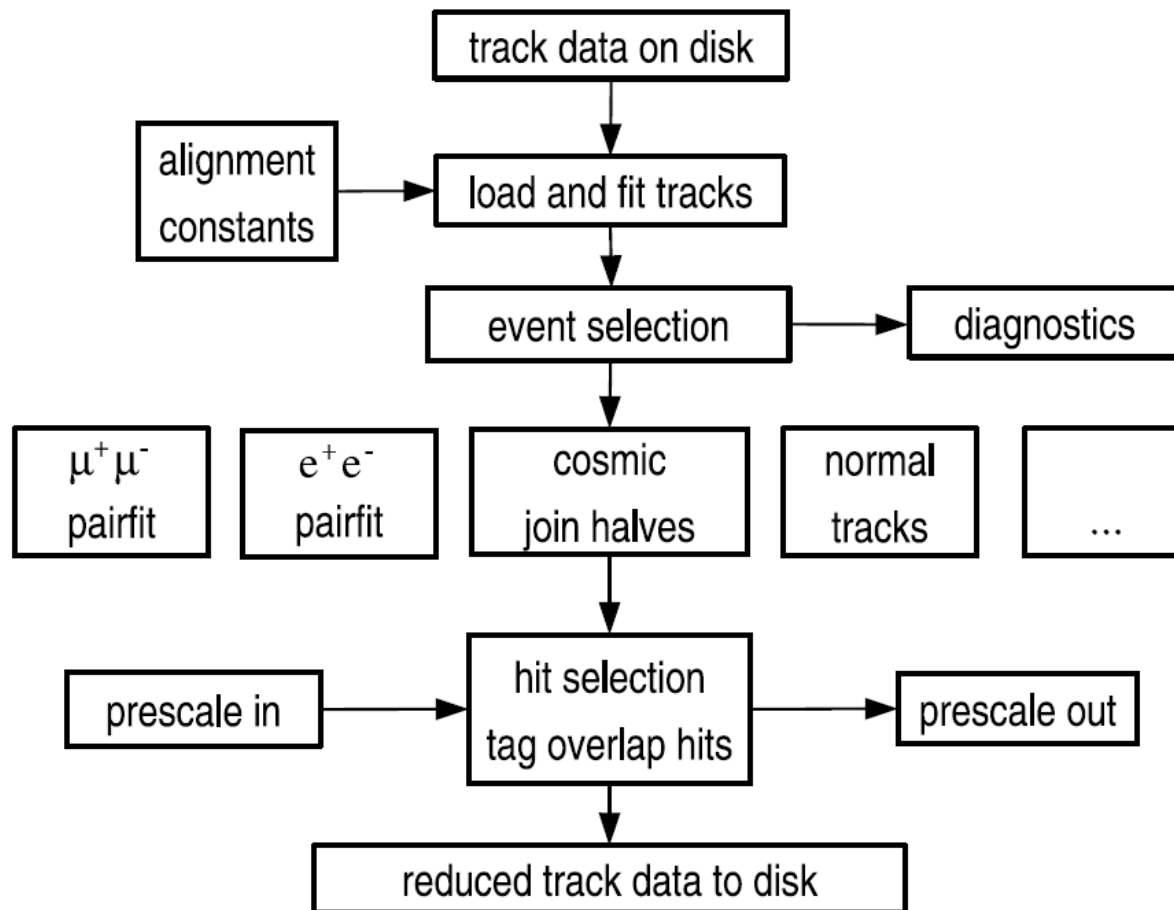
- Define five categories
(1) "normal" (2) $\mu^+\mu^-$ (3) e^+e^-
(4) cosmic (5) overlap hits
- Sequence
 - dedicated stream/skim/tag
 - apply cuts, tag events/track/hit
 - distribute uniformly over SVT, ϕ and Z readout, categories
- Select $\sim 50,000$ tracks
tag $\sim 3-4$ hits/track (out of 9-10)

DCH-only fit ω constraint (inverse curvature) greatly improve the momentum resolution of the constrained SVT-only track





Track/Hit Selection for SVT-LA



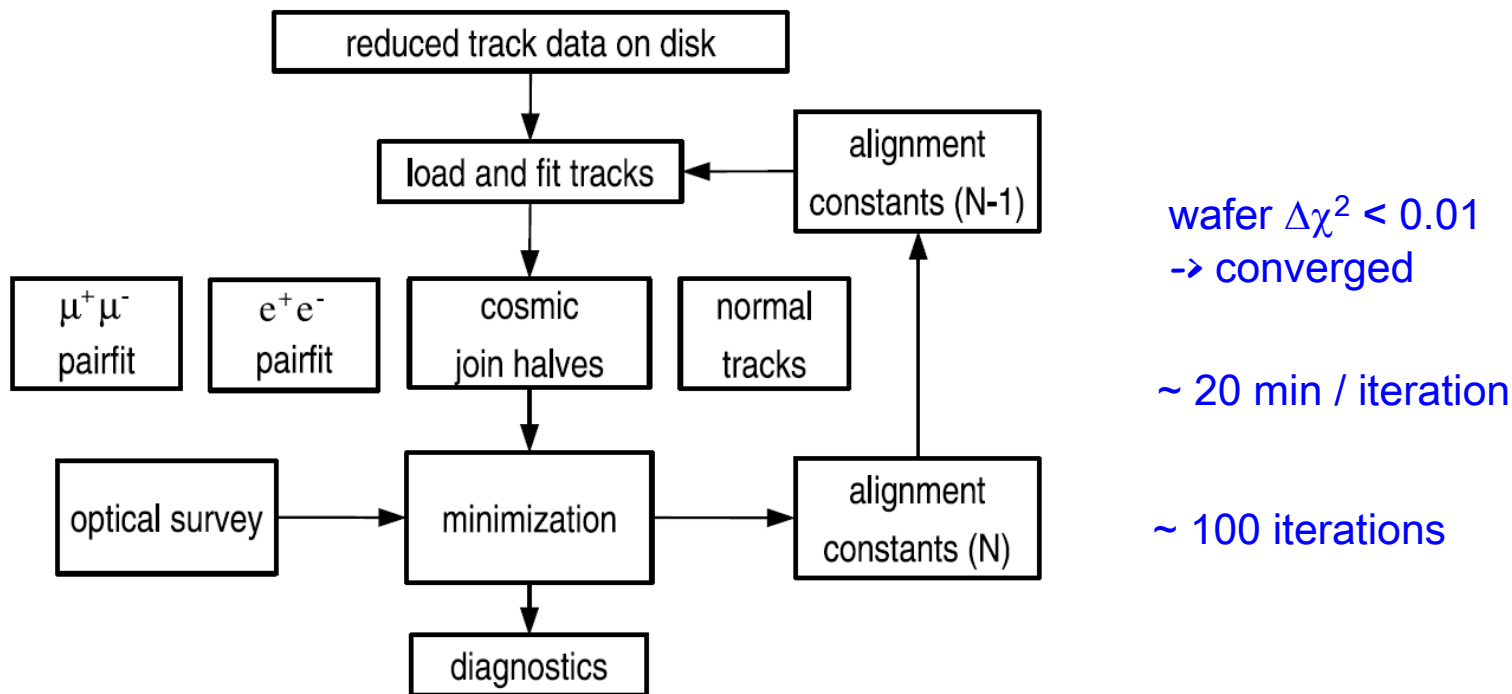
Sequence for the event, track, and hit selection, including calculation of prescale factors



Local Alignment Minimization Procedure

- Minimize 340 separate wafer χ^2 independently

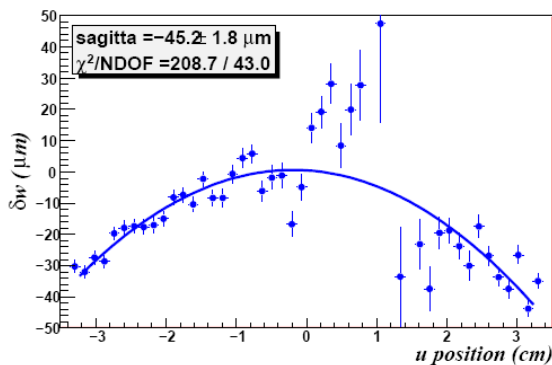
$$\chi^2 \equiv \sum_i^{\text{hits}} \underbrace{\epsilon_i^T(\Delta\mathbf{p}) \mathbf{V}_i^{-1} \epsilon_i(\Delta\mathbf{p})}_{\text{hit residuals}} + \underbrace{\epsilon_s^T(\Delta\mathbf{p}) \mathbf{V}_s^{-1} \epsilon_s(\Delta\mathbf{p})}_{\text{survey residuals}}$$





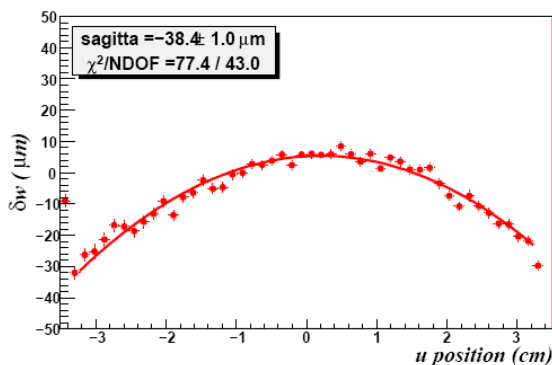
Wafer Curvature

- Radial position is measured by overlaps
 - ϕ overlap hits constrain circumference
 - assume flat wafer geometry



u and v hit residuals from high momentum tracks

- non-linear dependence indicates an **aplanar** wafer distortion, not described by the standard six local alignment parameters
- wafer bowed in the uw plane
simple bowing may not be the only aplanar distortion present
- systematic bias on the transverse impact parameter





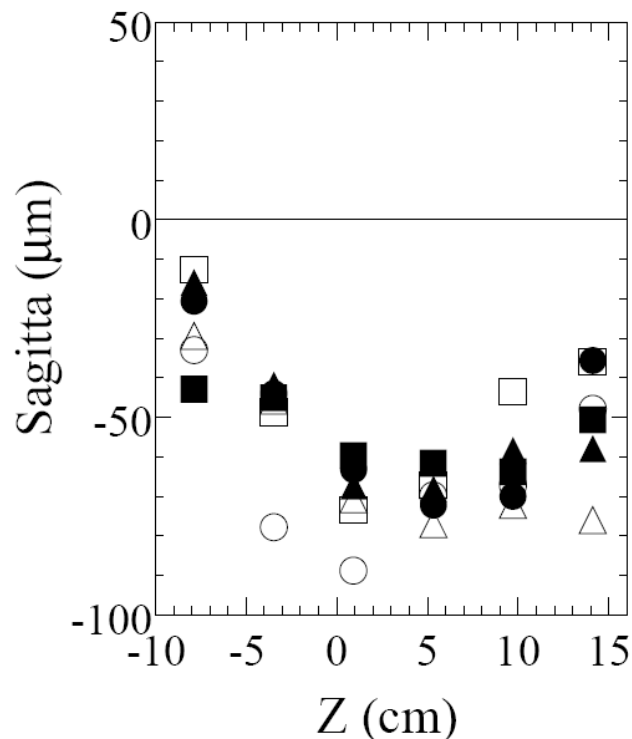
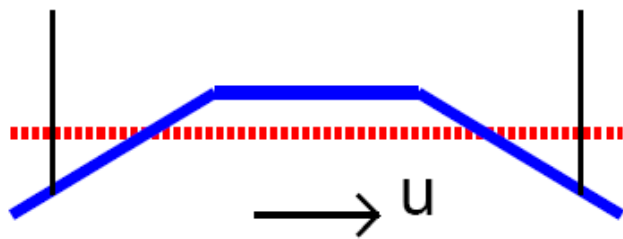
Wafer Curvature



The aplanar wafer distortions must be measured and corrected for the alignment procedure

- Wafer bowing in ϕ
- model by polygon for Z strips

$$\delta w(u) = (u^2 - u_0^2)/2R$$

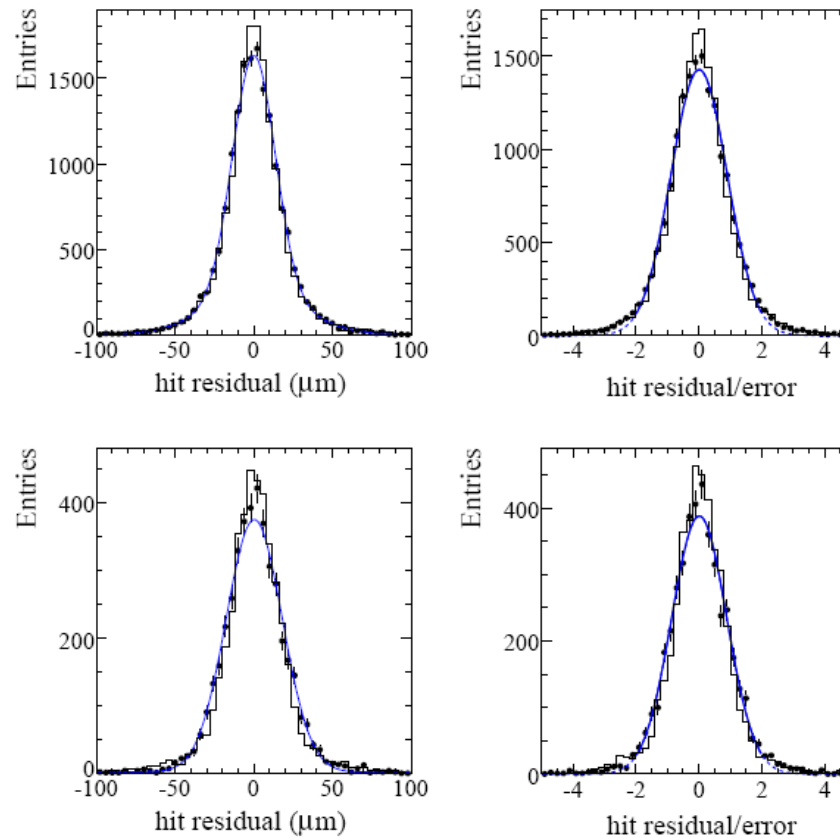


Measure the curvature radius R for each inner-layer wafer by fitting the average u and v residuals dependence on u

adding 84 more parameters



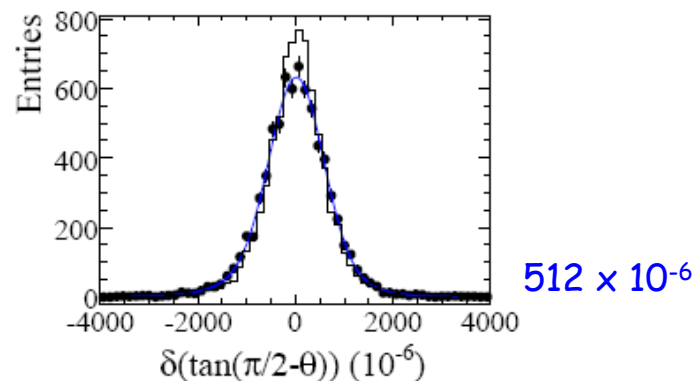
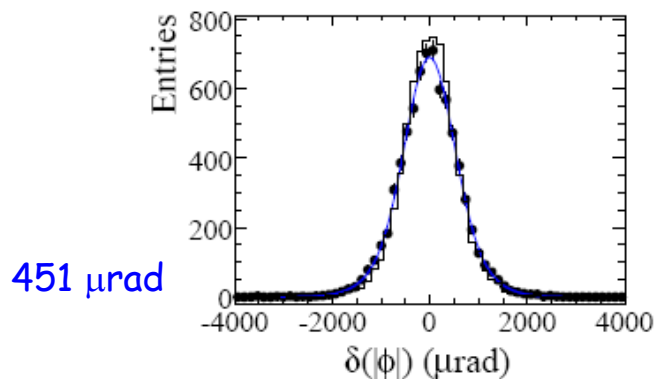
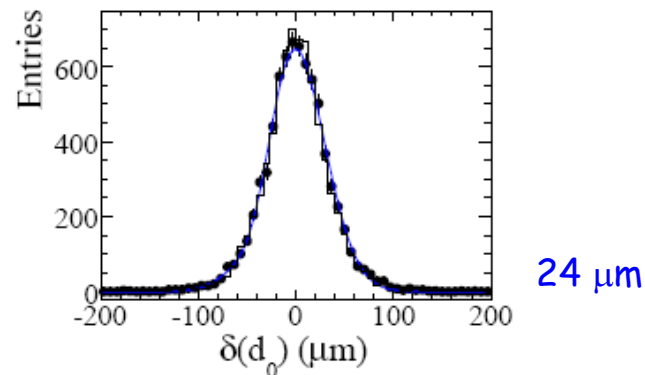
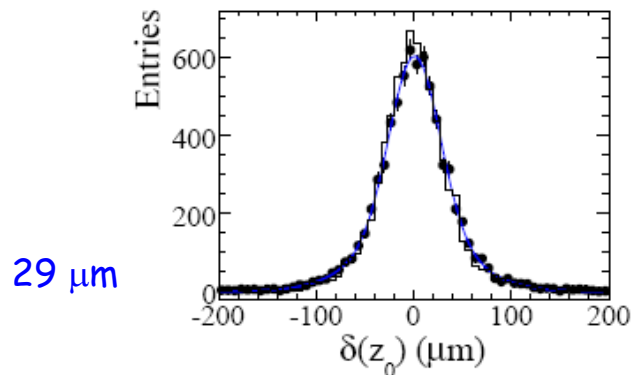
Validation of the Alignment



- Basic test of alignment self-consistency: **hit residuals**
 - Inner three layers using $e^+e^- \rightarrow \mu^+\mu^-$
 - **14 (13) μm** for data (MC) u hits, **18 (16)** for ν hits
 - Good agreement between data and MC



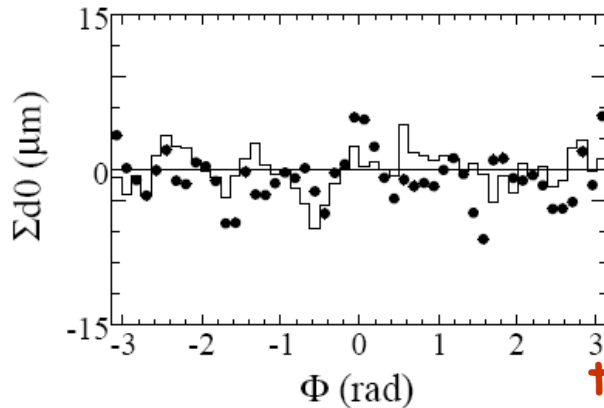
Validation of the Alignment



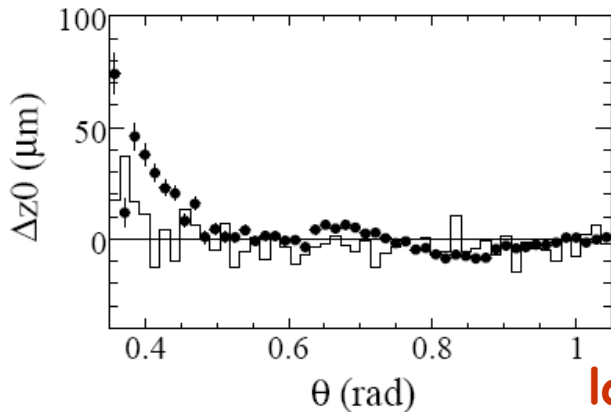
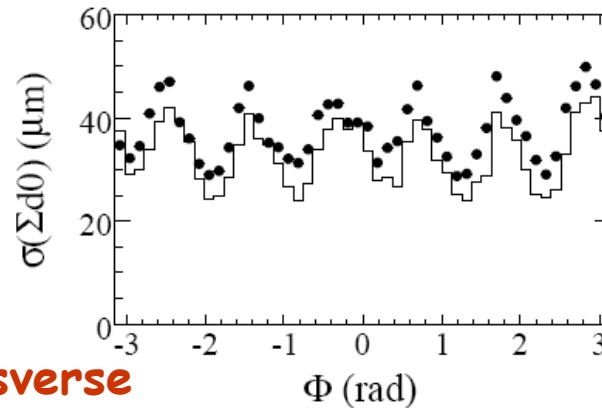
- High-level self-consistency test: **cosmic ray splitting**
 - incoming and outgoing branches as two separate tracks
 - fit using **SVT hits** plus a **DCH curvature** constraint



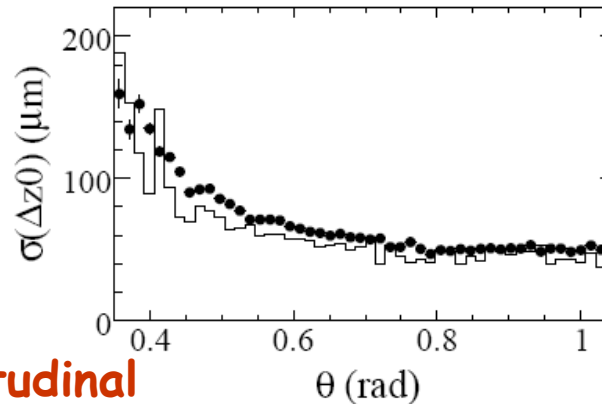
Validation of the Alignment



transverse



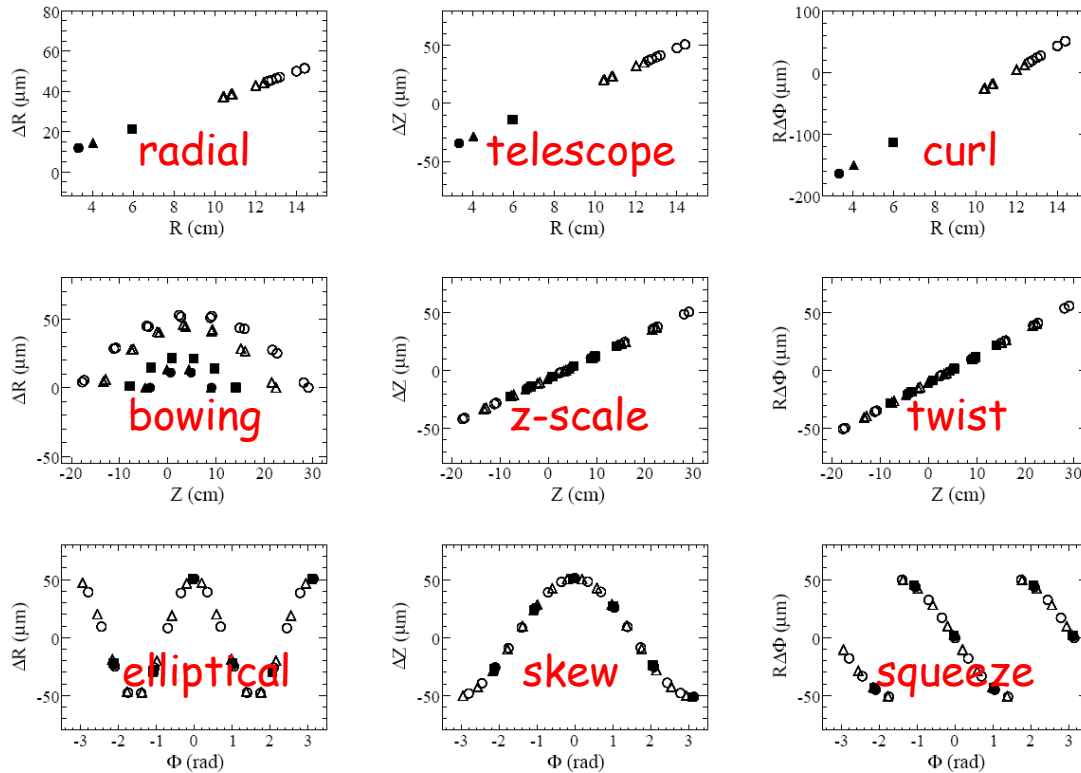
longitudinal



- Comparing the reconstructed origin points of the two tracks produced in $e^+e^- \rightarrow \mu^+\mu^-$
 - measure the impact parameter resolution
 - look for systematic biases left by the alignment



Validation of the Alignment Systematics

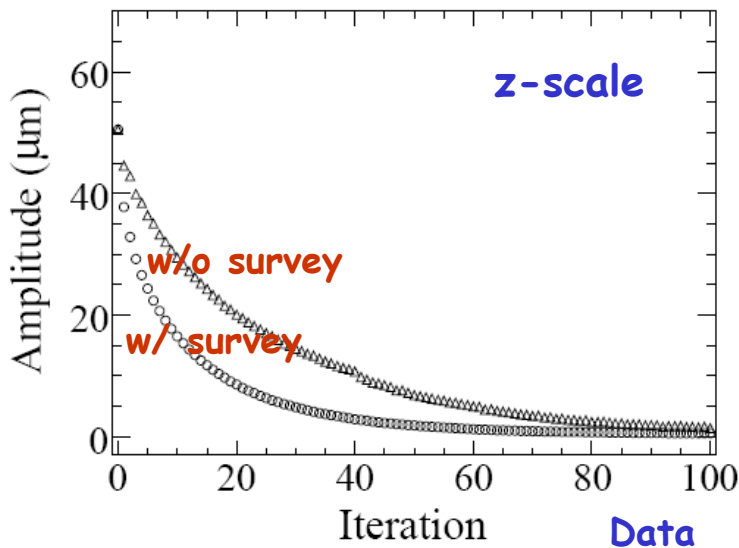


	Δr	Δz	$r\Delta\phi$
vs. r	radial scale	telescope	curl
vs. z	bowing	z -scale	twist
vs. ϕ	elliptical	skew	squeeze

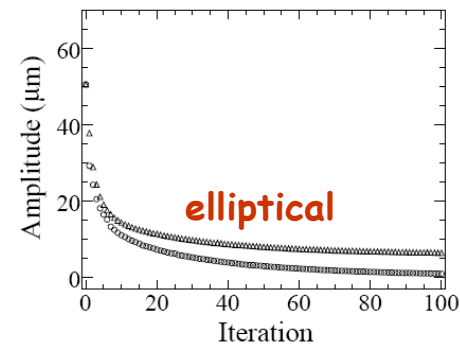
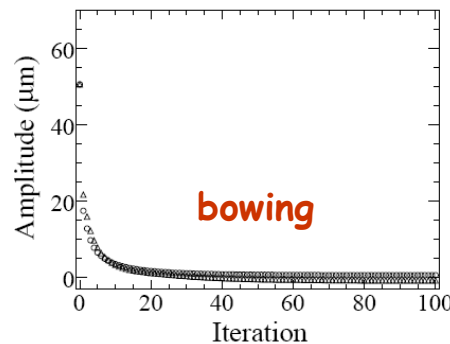
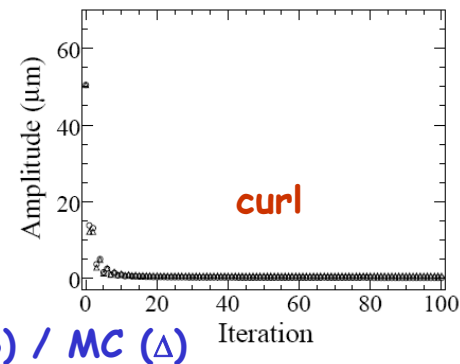
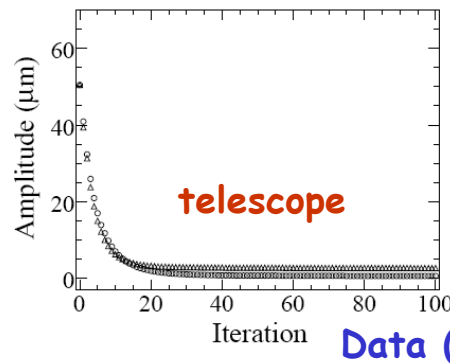
Nine distinct distorted initial conditions
Set the initial scale to $50\mu\text{m}$



Validation of the Alignment Systematics



Survey information improves the convergence and reduce the systematic error



- LA procedure capable of reducing global distortions to a negligible level

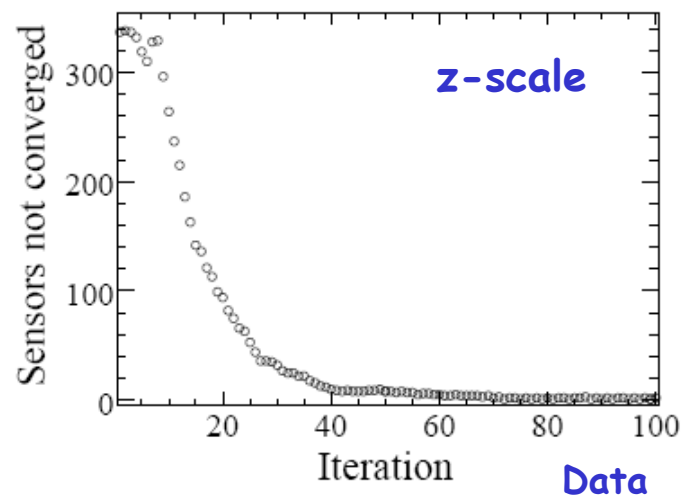


Validation of the Alignment Systematics

	Δr	Δz	$r\Delta\phi$
vs. r	radial	telescope	curl
decay (iterations)	5.6	5.1	1.3
distortion (μm)	0.7	0.5	0.1
vs. z	bowing	z -scale	twist
decay (iterations)	2.6	11.2	12.0
distortion (μm)	0.6	0.6	0.1
vs. ϕ	elliptical	skew	squeeze
decay (iterations)	11.8	33.6	32.0
distortion (μm)	0.9	4.9	4.5

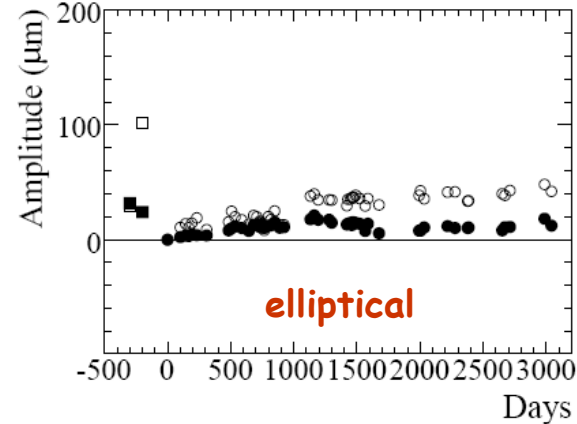
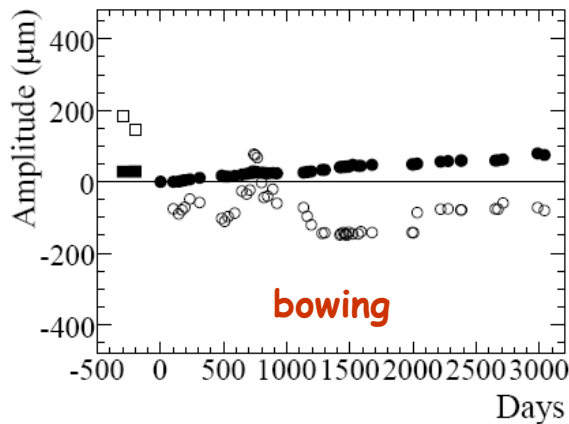
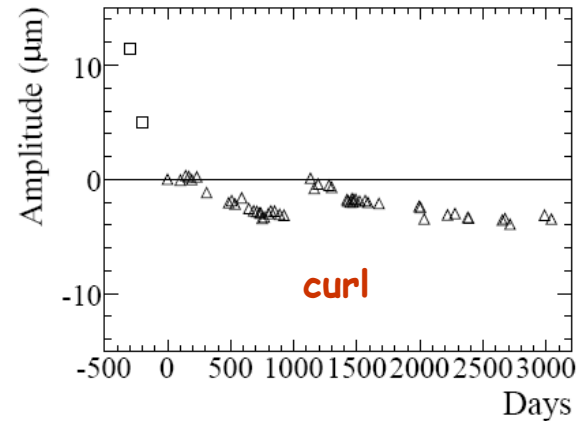
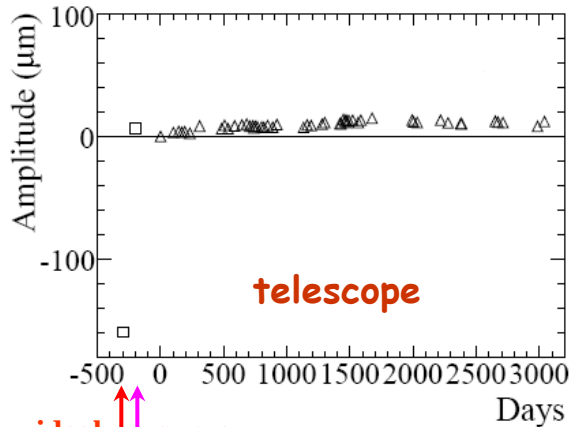
Decay time and remaining distortion

- Global distortions are the most weakly constrained deformations
- The order of 100 iterations necessary to solve for these deformations
- Convergence requirement chosen empirically to allow convergence of the global distortions





Validation of the Alignment Systematics

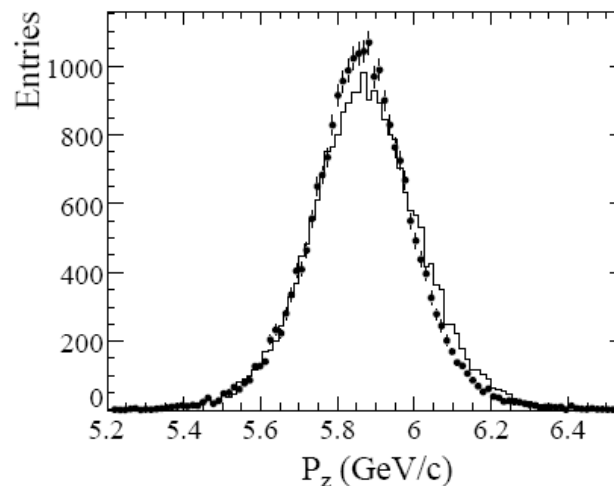
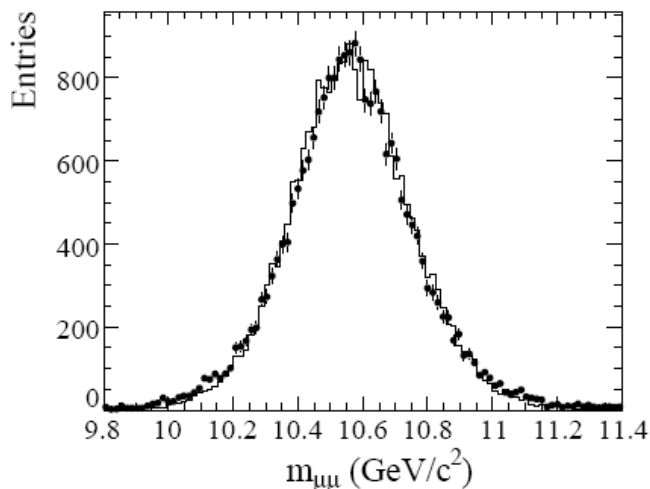


ideal ↑↑ survey

- **Time-dependence** of global distortion, compared to the initial day-one alignment Nov 1999 - Apr 2008 data
- Study of potential distortions places limits on systematic uncertainties in physics measurements



Fit for the e^+e^- Beam Energies



- Fit the average $\mu^+\mu^-$ **boost** and use it in the four-momentum pair constraint instead of the **initial state boost**
- Iterate, allowing a **simultaneous** extraction of the boost value and the geometrical constraints
 - makes the local alignment algorithm more stable
 - allow for monitoring the e^+e^- beam boost



Conclusions

- Described the procedure used to determine BaBar SVT local alignment
relative positions and orientations of the 340 wafers
- Satisfies the requirements placed on the SVT performance by the BaBar physics goals
- Robust against global distortions